

ABSTRACT

A heat resistant photosensitive resin composition having excellent film properties is provided by
5 constituting a photosensitive resin composition containing
(A) a polymer having an acid functional group and/or a
substituent derived therefrom, (B) a compound having at
least one substituent derived from an amine functional
group, (C) a photoreactive compound, and (D) a solvent.
10 Using this composition, a pattern with high resolution can
be produced, and thus an electronic part having a high
quality can be produced.